	© Copyright 2005. International and Pa	IPC, Bannockt	ourn, Illinois. A	Il rights reserved u ntions.	nder both	This docume level parts, t	ent is a declara he declaration	ation o 1 encor	f the substances npasses all lowe	within th r level ma	e manufactur terials for wl	er listed in hich the m	tem. Note: i nanufacture	if the item is an as r has engineering	sembly with lowe responsibility.
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplie	r Information														
Company name* Co				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2024-04-20			
Contact N	lame		Title - Contact				Phone - Contact*					Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative				Phone - Representative*				Email - Representative*				
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufactur		acturing Site Weight*		UOM	Unit Type			
	NJW3281G TO		TO-3P NPN POWER TRAN 250V)V	2024-04-20]	KR8		:	5184.55	mg	Each	
Manufa	cturing Proccess Informa	ntion													
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020		-STD-020 MSI	L Rating	Peak Process Body Temp		Body Temperatu	ature Max Time at Peak		Temperat	ure Numb	ber of Reflow Cyc	eles
	Matte Tin (Sn) - annealed			CU Alloy NA			0 C 30			seconds 3					
Comments	3														
or more	information regarding material	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).						
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	20.45	mg	Supplier	Silicon (Si)	7440-21-3		20.45	mg
Die Attach	25.85	mg	Supplier	Silver (Ag)	7440-22-4		0.3877	mg
			А	Lead (Pb)	7439-92-1	7a	24.1698	mg
			Supplier	Tin (Sn)	7440-31-5		1.2925	mg
Lead Frame	3425.52	mg	Supplier	Iron (Fe)	7439-89-6		3.4255	mg
			Supplier	Copper (Cu)	7440-50-8		3422.0945	mg
Mold Compound-Black	1694.84	mg		Brominated epoxy resin	proprietary data		25.4226	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		322.0196	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		20.3381	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1327.0597	mg
Plating	14.5	mg	Supplier	Tin (Sn)	7440-31-5		14.5	mg
Wire Bond - Al	3.39	mg	Supplier	Aluminum (Al)	7429-90-5		3.39	mg